

KEC CORPORATION



KEC



The Best Technology

Will be constantly challenged.

Company Name	KEC CORPORATION
Location	5, Mabang-ro, 10-gil, Seocho-gu, Seoul, Korea
Founded	Sep. 9th. 1969 (Spin off in 2006)
Capital	US\$ 39Mil.
Revenue	US\$ 192Mil. (2016)
President	Chang-sup,Hwang
Head Count	638people (as the end of 2016)
Product	Non-memory semiconductor (Transistor, Diode, IC, MOS...etc)





2. VISION & Management Philosophy



Achieve US\$600Mil. In 2020 (SSTR worldwide No.1)

Main Strategy

- More Products for SMALL SIGNAL TR, DIODE, Complex discrete
- Enlarge POWER (MOSFER, Power Module)

Creating electronic technologies is **Our Business**.
 Always thinking from an international perspective and working
 To develop ourselves to our full potential, **we strive to providing
 the finest products as well as help Improve the quality of life for all.**
 We share this joy with the society.



Worldwide No.1 semiconductor expert company

We would be a global leader moving forward all around
 The world.

KEC will always stay in progress toward advanced technology and
 know-how.
 Our challenge will never stop to be "worldwide No.1 in semiconductor"



chairman *Jung-So Kwak*

Craftsmanship's KEC

We pursue only one goal which's semiconductor from the time of Foundation 1969. KEC got acknowledged for faithful quality and superb Technology by worldwide electronic companies, which were achieved by Its ceaseless development in technology and innovation in management.

Semiconductor expert's KEC

By the year 2000, KEC got worldwide competitiveness in its major business Territory, SSTR and now expanding the market by challenging POWER Semiconductor for the goal to be No.1 at SSTR market in 2017 with the Total revenue of U\$ 600Mil.

World's smallest package's KEC

KEC will create our better future by going forward the most compact SMD Packages, Ultra-power-saving discrete, the most efficient Rf discrete... etc

Our challenges to be

"worldwide No.1 in semiconductor" will never stop.

Thank you.



4. History

1969~2000

- 1969 (Sep)** – Established as Korea Toshiba Co., Ltd
- 1970 (Mar)** – Started Transistor Production
- 1974 (Mar)** – Renamed to Korea Electronics Co.,Ltd.
- 1975 (Jun)** – Started IC Production
- 1979 (Oct)** – IPO (Initial Public Offering) Started Fabrication for semiconductor Devices
- 1988 (Jul)** – Established KEC Hong Kong (KEC-H) Sales Branch
- 1990 (Oct)** – Established KEC Thailand (KEC-T) Assembly Plant.
- 1995 (Ma)** – Established KEC Wuxi Assembly Plant
- 1995 (Sep)** – Moved HQ to Yangjae-Dong, Seoul
- 2000 (Mar)** – Implementation of ERP System
- 2000 (May)** – Renamed to KEC CORPORATION

2001~2009

- 2001 (Jun)** – Awarded Grand Prize of "2001 Korea's Best company of Value Management"
- 2003 (Dec)** – Received a "Best Product-SSTR" Award from Korea Dept. of Commerce.
- 2004 (Aug)** – Declaration of MOS Business
- 2005 (Sep)** – Started 6" Wafer Production in China FAB plant
- 2006 (Mar)** – Opened MOS FAB Plant in Korea
- 2007 (May)** – Achieved 30M\$ of monthly turnover
- 2008 (Aug)** – Started Sensor, Module, IGBT Production
- 2009 (Aug)** – MOU with Seoul Metropolitan Rapid Transit Corp. on developing IGBT Modules
- 2009 (Nov)** – Developed "Ultra Fast Recovery Diode" for Flat Panel display TV (First time in Korea)



2010~

- 2009 (Dec)** – Long-term supply contract of LED Chip with LG innotek
- 2010 (Apr)** – Long-term supply contract of LED Package with LG innotek
- 2010 (Apr)** – Joint development contract with Hyundai Mobis for Power Module of Hybrid car
- 2011 (Jan)** – Selected as "Best partner of LG innotek"
- 2011 (Apr)** – Launched new product "power Module for Electric Vehicles" product "High Power IGBT Chips" for the first time in Korea
- 2012 (Dec)** – Received UL Certification of the General Purpose Power Module
- 2013 (Nov)** – 11 Obtained the patent on the Green Die-bonding technology
- 2013 (Dec)** – 2013. 12 Received SQ Certification from HYUNDAI-KIA Motors
- 2014 (Aug)** - Developed Low VF SBD applying Trench Process
- 2015 (Feb)** - Developed and produced Ultra-Low Current consumption Detector, Reset IC certifying AEC-Q100
- 2016 (Jul)** - Developed the next generation Synchronous Rectification MOSFET



✓ Production



✓ Supply NETWORK

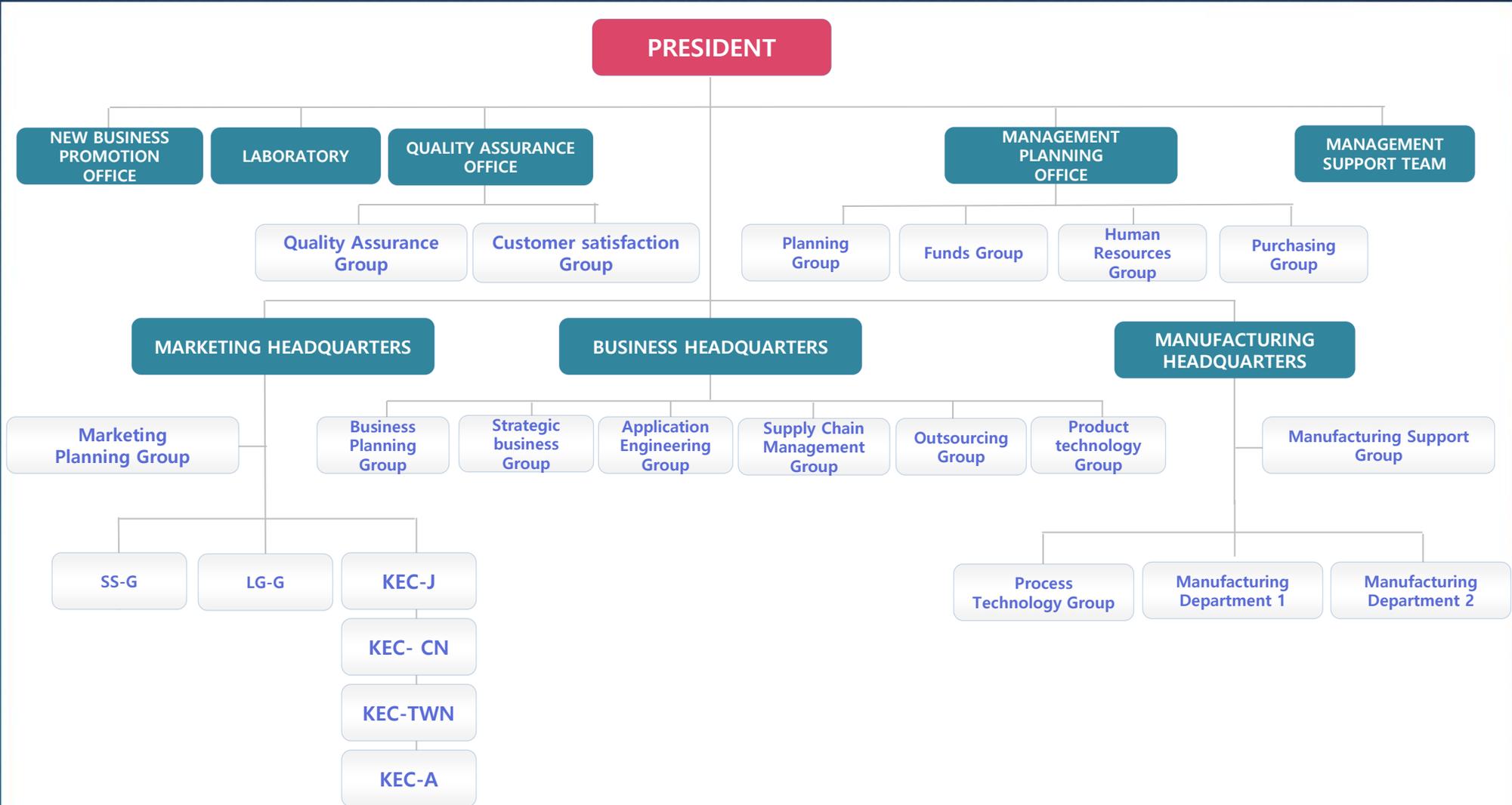


Globalization

- ① Sales Site : 11 (Korea :2 Sales Offices / Overseas : 5 Branches and 4 office)
- ② Production Site : 54 (Korea : FAB 1, Assembly 1 / Overseas : Assembly 2)
- ③ R&D : 27개 (Korea 1 / Japan1)



6. Organization



BJT

- ✓ General Purpose Transistor
- ✓ General Purpose BRTs
- ✓ Small Signal Junction Field Effect Transistor
- ✓ RF/VHF/UHF Transistor
- ✓ High hFE Transistor
- ✓ Low VCE(sat) Transistor
- ✓ Low Noise Transistor
- ✓ Darlington Transistor
- ✓ High Voltage Transistor

DIODE

- ✓ Small signal Switching Diode
- ✓ Schottky Barrier Diode(SBDs)
- ✓ Zener Diode
- ✓ TVS Diode
- ✓ Varactor Diode(AFC Application for FM, AM Tuning, ...)
- ✓ Fast Recovery Diode(FRDs)
- ✓ Band Switching Diode
- ✓ PIN Diode

INTERGRATED CIRCUIT

- ✓ Transistor Array & Interface Driver
- ✓ Voltage Detector
- ✓ OP Amp & Comparator
- ✓ Logics MOS
- ✓ Voltage Stabilizer
- ✓ Voltage Regulator
- ✓ Power Supply Controllers

MOSFET

- ✓ High Voltage MOSFETs
- ✓ Low Voltage MOSFETs
- ✓ RF MOSFETs
- ✓ S MOSFETS

POWER MODULE

AUTOMOTIVE DECIVE

- ✓ Alternator Diode
- ✓ Surge Absorber

IGBT

7. Main Product Line up – ㉞ Product Line up by Package

SMD



SOT-23
2.93x1.3x1.0



SOT-89
4.7x2.5x1.5



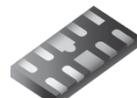
SMF
2.6x1.6x0.98



SMA
4.5x2.6x2.0



VSC
(SOD-723)
1.0x0.6x0.5



ULP-10
2.5x1.0x0.58



USM
(SOT-323)
2.0x1.25x0.9



USC
(SOD-323)
1.7x1.25x0.9



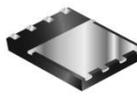
ESC
(SOD-523)
1.2x0.8x0.6



SOT-223
6.5x3.5x1.8



USQ/V/6
(SOT-353)
2.0x1.25x0.9



PDFN56
5.1x6.05x1.1



USF
1.9x1.25x0.6



VSM
(SOT-23)
1.2x0.8x0.5



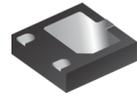
TFSC
0.8x0.6x0.38



ELP-2
0.6x0.3x0.28



ULP-2
1.0*0.6*0.38



UDFN2020-3
2.0x2.0x0.6



FLP-8
4.8x3.9x1.6



FLP-16
9.9x3.9x1.6



DPAK/5
6.6x6.1x2.3



D2PAK/5
9.8x8.8x4.0



T(E)SQ/V/6
2.9x1.6x0.7



UDFN1608-2
1.6x0.8x0.37

THD



TO-92
4.8x4.7x3.7



IPAK
6.6x6.1x2.3



DIP-8
9.6x6.45x3.8



TO-126
8.3x11.0x3.4



TO-220AB
10.0x15.0x4.7



DIP-16
25.1x6.4x3.3



TO-220IS
10.0x15.0x4.5



TO-3P(N)
15.9x20.0x4.8



TO-3P(H)IS
16.3x20.0x5.5



TO-247
16.3x20.8x5.0



8. Main Customers

[KOREA]



[JAPAN]



[ASIA]



[USA/EUROPE]



[Appendix 1 : Partnerships](#)

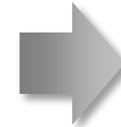


9. Production site

<Fabrication Site>

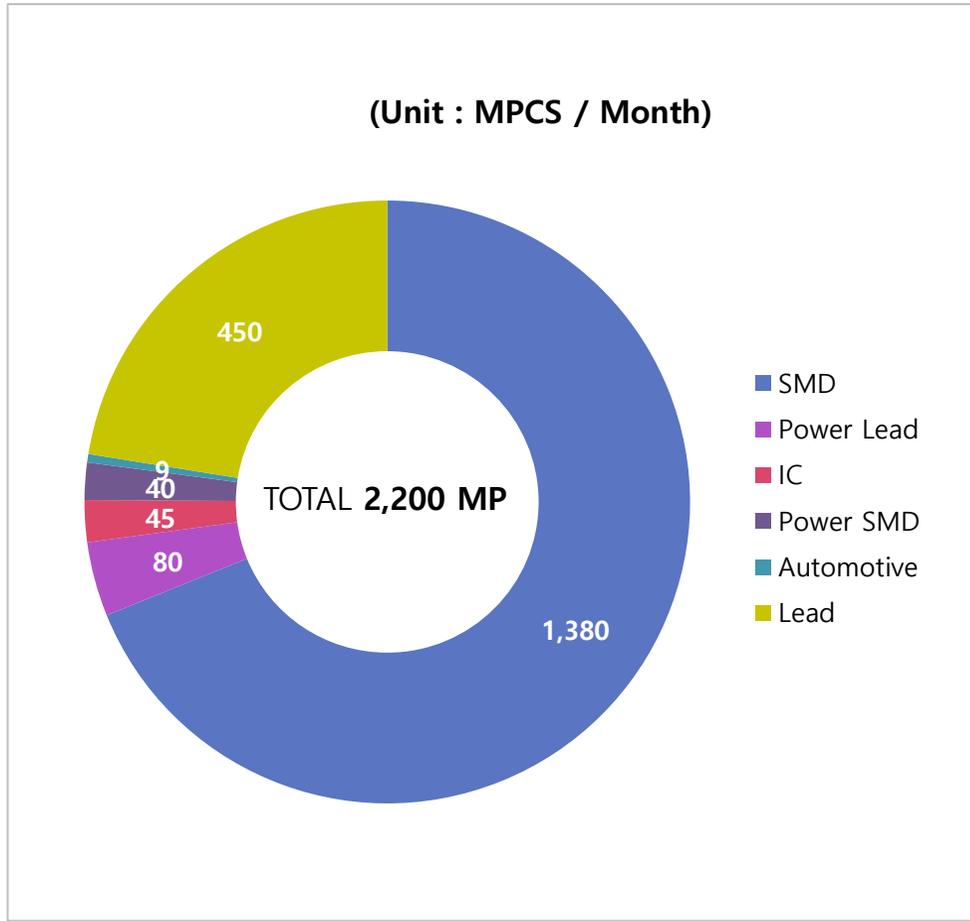


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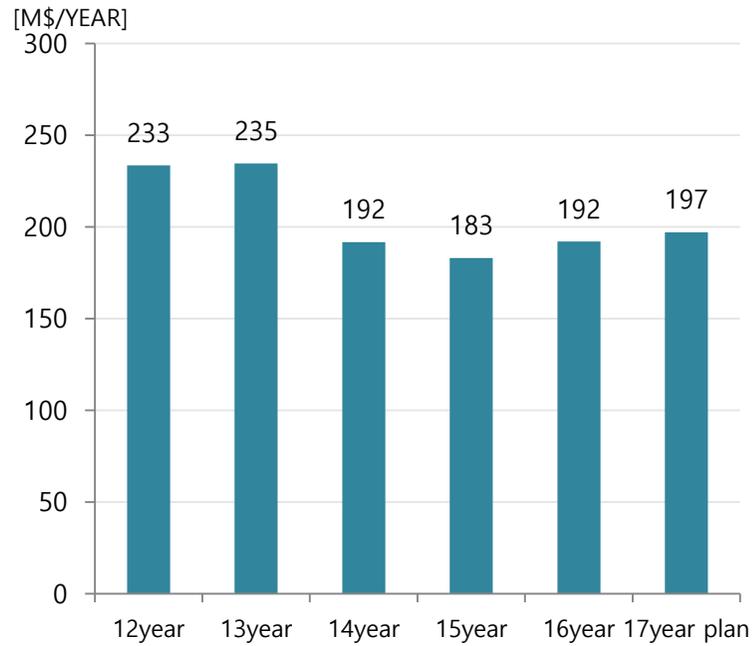
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Sales Trends



Thank you